

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shang-Chun Chen	09/10/2013
Cha-Hsin Lin	09/12/2013
Yu-Chen Hsin	09/10/2013
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14033524
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ATTORNEY DOCKET NUMBER:	45488-US-PA
NAME OF SUBMITTER:	Belinda Lee
Signature:	/Belinda Lee/
Date:	09/26/2013
Total Attachments: 2 source=45488us_Assgn#page1.tif source=45488us_Assgn#page2.tif	

CH \$40.00 14033524

ASSIGNMENT

WHEREAS,

1. Shang-Chun Chen
2. Cha-Hsin Lin
3. Yu-Chen Hsin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Shang-Chun Chen
Sole or First Joint Inventor: Shang-Chun Chen

Date: 2013.9.10

Signature: Cha-Hsin Lin
Second Joint Inventor (if any): Cha-Hsin Lin

Date: 2013.9.12

Signature: Yu-Chen Hsin
Third Joint Inventor (if any): Yu-Chen Hsin

Date: 2013.9.10